## DECLARATION FOR PATENT APPLICATION

I believe I am the original, first an (if plural names are listed below) invention entitledBIND specification of which is attached	of the subject matter which is ER	claimed and for which a paten		
	as United States Application Number of and was amended on			
I hereby state that I have reviewed as amended by any amendment re		of the above identified specific	ation, includin	g the claims,
I acknowledge the duty to disclose	e information which is materia	al to patentability as defined in	37 CFR § 1.56	5.
I hereby claim foreign priority ber or inventor's certificate, or § 365( than the United States, listed belo- certificate, or PCT International a claimed.	<ul> <li>a) of any PCT International ap w and have also identified bel</li> </ul>	pplication which designated at ow any foreign application for	least one count patent or inver	try other ntor's
Prior Foreign Application(s)		Priority Date	Priority Cla	imed
Patent Application 2002-311772 (Number)		25/10/2002 (Day/Month/Woon Filed)	Yes _ ⊠	No .
Prior Foreign Application(s)	(Country) (FC1)	(Day/Month/Year Filed) Priority Date	Priority Cla	imed
Patent Application 2003-152410 (Number)	Japan (Country) (PCT)	29/05/2003 (Day/Month/Year Filed)	Yes	No
Prior Foreign Application(s)	, , ,	Priority Date	Priority Cla	imed
Patent Application 2003-190647 (Number)	Japan (Country) (PCT)	02/07/2003 (Day/Month/Year Filed)	Yes _ ⊠	No
I hereby claim the benefit under 3.	5 U.S.C. § 119(e) of any Unit			ow.
(Application Number)		(Filing Date)		
(Application Number)		(Filing Date)		

I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. § 112, I acknowledge the duty to disclose information which is material to

patentability as defined in 37 CFR § 1.56 which became available between the filing date of the prior application and the

national or PCT International filing date of this application.

(Application Number)	(Filing Date)	(Status –	patented, pending, abandoned)		
(Application Number)	(Filing Date)	(Status –	patented, pending, abandoned)		
I hereby appoint the following attorney Patent and Trademark Office connected		plication a	nd to transact all business in the		
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.					
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